



Epochal-400

oligomer · monomer · photoinitiator· additive

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Epochal-400 Coating anhydride curing agent

Content: 99.5%

Appearance: Pale yellow powder

Particle size: 5-10 μm

Melting point: 190°C

Characteristics: This resin-coated micron-sized anhydride curing agent contains carboxyl functional groups. As a sealing and curing agent for epoxy resins and a crosslinking agent for polyimides, it is non-toxic, low in volatility, chemically resistant, has good weather resistance, and high heat resistance.

Applications: Coatings requiring high temperature and corrosion resistance, heat-resistant insulating laminates, composite molded insulating materials, high-temperature inks, and adhesives. It can withstand long-term high-temperature testing at 250-300°C or short-term high-temperature testing at 400°C.

Recommended dosage: 25-80%, with temperature resistance increasing proportionally to the amount added.

Curing temperature: Solid powder applications: 190-200°C

Solvent-based applications: 150-180°C